



Material Content Data Sheet



Sales Product Name		BTS452R		Issued		9. January 2019			
MA#		MA001868494							
Package		PG-TO252-5-11		Weight*		355.75 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.188	0.62	0.62	6151	6151	
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172		
	non noble metal	iron	7439-89-6	0.205	0.06		575		
	non noble metal	copper	7440-50-8	204.243	57.40	57.48	574113	574860	
	non noble metal	aluminium	7429-90-5	0.156	0.04	0.04	438	438	
wire	non noble metal	aluminium	7429-90-5	0.156	0.04	0.04	438	438	
encapsulation	organic material	carbon black	1333-86-4	1.414	0.40		3976		
	plastics	epoxy resin	-	24.753	6.96		69579		
	inorganic material	silicondioxide	60676-86-0	115.278	32.40	39.76	324038	397593	
leadfinish	non noble metal	tin	7440-31-5	5.072	1.43	1.43	14258	14258	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	214	215	
solder	non noble metal	tin	7440-31-5	0.046	0.01		130		
	noble metal	silver	7440-22-4	0.058	0.02		162		
	non noble metal	lead	7439-92-1	2.203	0.62	0.65	6193	6485	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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